



**QUALIFICATION REPORT SUMMARY**  
**RELIABILITY LABORATORY**

**PCN #: JAON-11SIPZ900-BCDM000046**

**Date**  
**March 24, 2016**

**Qualification of Microchip 8 inch Fabrication site for Micrel products  
manufactured with the BCDM Process Technology.**



PACKAGE QUALIFICATION RESULTS						
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	Rej/ss	COMMENTS	
Level 3 Pre-conditioning Flow	JESD22-A113	1543P	V21618566.000MQB	0/321		
		1543P	V21618566.100MQA	0/143		
		1543P	V21618566.111MQA	0/143		
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS	
PRESSURE POT  With Level 3 Pre-conditioning Tpeak + 260°C 3X Reflow	JESD22-A102	1543P	V21618566.000MQB	0/45		
	Ta = +121°C/100%RH	1543P	V21618566.100MQA	0/45		
	15 PSIG	1543P	V21618566.111MQA	0/45		
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	96 HR Rej/ss	COMMENTS	
HAST  With Level 3 Pre-conditioning  Tpeak + 260°C 3X Reflow	JESD22-A110 (BIASED)	1543P	V21618566.000MQB	0/45		
	Ta = +130°C/85%RH	1543P	V21618566.100MQA	0/45		
	VCC = +26V	1543P	V21618566.111MQA	0/45		
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	500 CY Rej/ss	COMMENTS	
TEMP CYCLE  With Level 3 Pre-conditioning Tpeak + 260°C 3X Reflow	JESD22-A104	1543P	V21618566.000MQB	0/45		
	Ta = -65°C / +150°C	1543P	V21618566.100MQA	0/45		
		1543P	V21618566.111MQA	0/45		
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	1000 HR Rej/ss	COMMENTS	
HTSL  High Temperature Storage Life Tpeak + 260°C 3X Reflow	JESD22-A103  Ta = +150°C	1543P	V21618566.000MQB	0/76		
TEST DESCRIPTION	METHOD/CONDITIONS	DATE CODE	LOT ID.	500 HR Rej/ss	1000 HR Rej/ss	COMMENTS
HTSL  High Temperature Storage Life Tpeak + 260°C 3X Reflow	JESD22-A103  Ta = +175°C	1543P	V21618566.000MQB	0/76	0/76	
FLAMMABILITY	UL-94V-0  Certified	All mold compounds used by Micrel meet this standard. See the UL website on-line list of material flammability certifications. Micrel requires a Certificate of Compliance from the assembly house and we verify the certifications on the web.				